



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN# 20250110001.2A

**Bond wire removal and datasheet update for select F65 devices
Change Notification / Sample Request**

Date: June 25, 2025
To: MOUSER PCN

Dear Customer:

PCN Revision A is to announce the retraction of the ExtR wire bond change from this notification.

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

Texas Instruments requires acknowledgement of receipt of this notification within 60 days of the date of this notice. Lack of acknowledgement of this notice within 60 days constitutes acceptance and approval of this change. If samples or additional data are required, requests must be received within 60 days of this notification.

The changes discussed within this PCN will not take effect any earlier than the proposed first ship date on Page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice or to provide acknowledgement of this PCN, you may contact your local Field Sales Representative or the change management team.

For sample requests or sample related questions, contact your local Field Sales Representative.

TI values customer engagement and feedback related to TI changes. Customers should contact TI if there are questions or concerns regarding a change notification.

Sincerely,

Change Management Team
SC Business Services

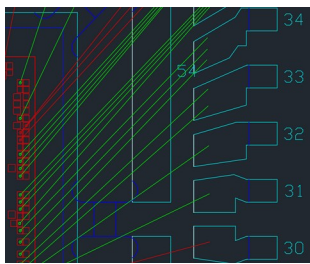
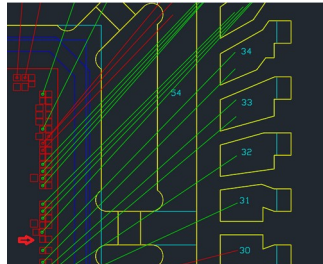
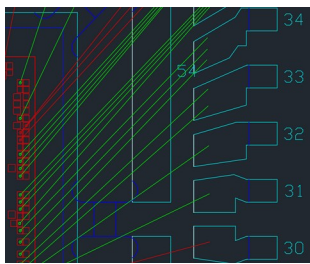
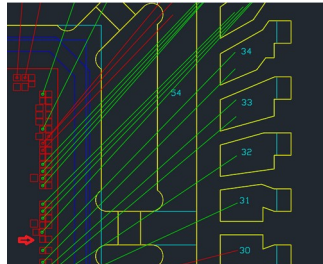
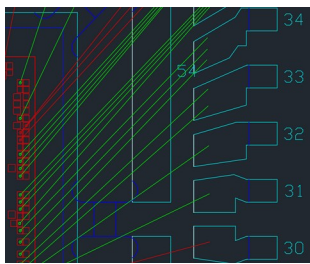
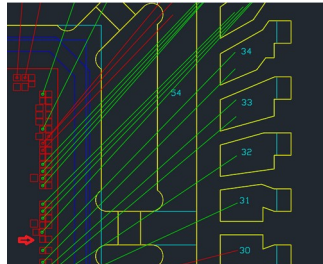

20250110001.2A
Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, you have recently purchased these devices. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
F2800157EPHPQ1	NULL
F2800156EPHPQ1	NULL
F2800156EPHPRQ1	NULL

Technical details of this Product Change follow on the next page(s).

PCN Number:	20250110001.2A	PCN Date:	June 25, 2025									
Title:	Bond wire removal and datasheet update for select F65 devices											
Customer Contact:	Change Management Team	Dept:	Quality Services									
Proposed 1st Ship Date:	July 16, 2025	Sample requests accepted until:	N/A									
Change Type:												
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design									
<input checked="" type="checkbox"/>	Assembly Process	<input checked="" type="checkbox"/>	Data Sheet									
<input type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change									
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site									
<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process									
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Material									
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Process									
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Site									
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Material									
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Process									
PCN Details												
Description of Change:												
<p>PCN Revision A is to announce the retraction of the ExtR wire bond change from this notification.</p> <p>Remove ExtR wire bond (pin 34- GPIO19,X1) and data sheetn update for the products listed in the "Product Affected" section of this document.</p> <p>Construction differences are as follows:</p> <p>Wire bonding diagram:</p> <table border="1"> <thead> <tr> <th></th> <th>From</th> <th>To</th> </tr> </thead> <tbody> <tr> <td></td> <td></td> <td></td> </tr> <tr> <td>ExtR wire bond- (GPIO19,X1 pin 34)</td> <td>With</td> <td>Without</td> </tr> </tbody> </table>					From	To				ExtR wire bond- (GPIO19,X1 pin 34)	With	Without
	From	To										
												
ExtR wire bond- (GPIO19,X1 pin 34)	With	Without										
<p>The datasheets will be changing as a result of the above mentioned changes. The datasheet change details can be reviewed in the datasheet revision history. The links to the revised datasheets are available in the table below.</p>												
		<p>TMS320F2800157-Q1, TMS320F2800157, TMS320F2800156-Q1, TMS320F2800155-Q1 TMS320F2800155, TMS320F2800154-Q1, TMS320F2800153-Q1, TMS320F2800152-Q1 SPRSP68C – JANUARY 2023 – REVISED JANUARY 2025</p>										

Changes from November 21, 2023 to January 9, 2025			Page
• This Revision History lists the changes from SPRSP68B to SPRSP68C.			1
• <i>Device Comparison</i> table: Removed "INTOSC with ExtR accuracy" row and associated footnote.			7
• <i>48-Pin PHP PowerPAD™ Thermally Enhanced Thin Quad Flatpack (Top View)</i> figure: Added footnote about GPIO226 and GPIO228.			11
• <i>32-Pin RHB Very Thin Quad Flatpack No Lead (Top View)</i> figure: Added footnote about GPIO226 and GPIO228. Added footnote about GPIO227 and GPIO230.			11
• <i>Pin Attributes</i> table: Removed ExtR from X1 pin description.			15
• <i>Digital Signals</i> table: Removed ExtR.			34
• <i>Digital Inputs and Outputs on ADC Pins (AGPIOs)</i> section: Updated section.			41
• <i>Absolute Maximum Ratings</i> table: Added additional information on input clamp current rows. Added two new footnotes.			47
• <i>Recommended Operating Conditions</i> table: Added new footnote related to Vin row.			47
• <i>Delay Blocks</i> section: Removed reference to external VREG.			65
• <i>Internal 1.2-V LDO Voltage Regulator (VREG)</i> section: Removed "It is enabled by tying the VREGENZ pin low" sentence.			65
• <i>VDD Decoupling</i> section: Updated Configuration 1 and Configuration 2.			65
• <i>Power Management Module Operating Conditions</i> table: Updated C _{VDD} TOTAL.			71
• Removed <i>INTOSC2 with External Precision Resistor – ExtR</i> section.			88
• <i>GPIO Assignments</i> section: Updated <i>CAN-FD Boot Options</i> table and <i>Parallel Boot Options</i> table.			179
• <i>Package Symbolization</i> figures: Updated definition of G4 in all <i>Package Symbolization</i> figures.			212
• <i>Documentation Support</i> section: Added <i>Migrating Software From 8-Bit (Byte) Addressable CPUs to C28x CPU</i> to <i>Application Notes</i> section.			217
• <i>Documentation Support</i> section: Added <i>Hardware Design Guide for F2800x C2000™ Real-Time MCU Series Application Note</i> .			217

Product Folder	Current Datasheet Number	New Datasheet Number	Link to full datasheet
TMS320F280015x	SPRSP68B	SPRSP68C	http://www.ti.com/product/TMS320F2800157

Reason for Change:			
Bond wire removal – removing ExtR support for INTOSC2			
Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):			
None			
Changes to product identification resulting from this PCN:			
None			
Product Affected:			
F2800156EPHPQ1	F2800156EPHPRQ1	F2800157EPHPQ1	F2800157EPHPRQ1

ZVEI IDs: SEM-DS-01, SEM-PA-08

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.

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